

Title (en)  
COMPONENT MOUNTING MACHINE

Title (de)  
KOMPONENTENMONTAGEMASCHINE

Title (fr)  
MACHINE DE MONTAGE DE COMPOSANTS

Publication  
**EP 3554207 A4 20191211 (EN)**

Application  
**EP 16924030 A 20161212**

Priority  
JP 2016086912 W 20161212

Abstract (en)  
[origin: EP3554207A1] A component mounting machine includes a mounting head configured to select and execute an individual mode in which lifting and lowering is performed for each of multiple holding tools, each of which holds a component and a collective mode in which the holding tools are lifted and lowered collectively; a memory section configured to store multiple collective lifting and lowering scheduled groups in each of which the components of which the number is the same as the number of holding tools are grouped; and a control section configured to subsequently execute holding of the component by the holding tool, dipping of the component into a coating agent, and mounting of the component on a board. In a case where a component for which the holding by the holding tool is to be skipped is included in the collective lifting and lowering scheduled group, the control section prohibits the holding of the component in the group, and allocates a component, for which the holding by the holding tool is not to be skipped, in the group, as a component in a new group. In a case where the number of components in the new group is the same as the number of holding tools, the dipping for the new group is performed in the collective mode, and in a case where the number of components in the new group is smaller than the number of holding tools, the dipping for the new group is performed in the individual mode for each holding tool to which the component is allocated.

IPC 8 full level  
**H05K 13/04** (2006.01)

CPC (source: EP US)  
**H05K 13/04** (2013.01 - EP); **H05K 13/0408** (2013.01 - US); **H05K 13/0469** (2013.01 - EP); **H05K 13/08** (2013.01 - US)

Citation (search report)

- [XAI] WO 2012136733 A1 20121011 - MICRONIC MYDATA AB [SE], et al
- [A] DIETER FRIEDRICH ET AL: "SMT-the New Surface Mount Technology for Printed Circuit Boards", SIEMENS COMPONENTS,, vol. XXI, no. 6, 1 December 1986 (1986-12-01), pages 211 - 221, XP001454616
- See references of WO 2018109807A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 3554207 A1 20191016; EP 3554207 A4 20191211; EP 3554207 B1 20211124**; CN 110024508 A 20190716; CN 110024508 B 20201127; JP 6718521 B2 20200708; JP WO2018109807 A1 20190808; US 11032959 B2 20210608; US 2020068756 A1 20200227; WO 2018109807 A1 20180621

DOCDB simple family (application)  
**EP 16924030 A 20161212**; CN 201680091300 A 20161212; JP 2016086912 W 20161212; JP 2018556041 A 20161212; US 201616466852 A 20161212